

BQ25175 スタンドアロン 1 セル 800mA リニア・バッテリー・チャージャ、充電電圧 4.35V、充電表示機能付き

1 特長

- 最大 30V の入力電圧に対応
- 自動スリープ・モードによる消費電力低減
 - 350nA のバッテリー・リーク電流
 - 充電ディセーブ時の入力リーク電流 80μA
- 1 セルのリチウムイオンおよびリチウムポリマをサポート
- 4.35V 固定のバッテリー・レギュレーション電圧
- 外付け抵抗によりプログラム可能な動作
 - ISSET により充電電流を 10mA～800mA に設定
- 高精度
 - ±0.5% の充電電圧精度
 - ±10% の充電電流精度
- 充電機能
 - プリチャージ電流: ISSET の 20%
 - 終了電流: ISSET の 10%
 - NTC サーミスタ入力によるバッテリー温度監視
 - 低温および高温時の充電無効化
 - 低温時充電は ISSET の 20%
 - TS ピンによる充電機能の制御
 - ステータスおよびフォルト表示用のオープン・ドレイン出力
- フォルト保護機能内蔵
 - 6.6V の IN 過電圧保護
 - 1000mA の過電流保護
 - サーマル・レギュレーション 125°C、サーマル・シャットダウン保護 150°C
 - OUT 短絡保護
 - ISSET ピンの短絡 / 開放保護

2 アプリケーション

- スマート追跡機能
- 完全ワイヤレス・ヘッドセット
- スマート・リモート・コントロール
- パルス・オキシメータ (血中酸素飽和度計)
- 血糖値測定器

3 概要

BQ25175 は、1 セルのリチウムイオン、リチウムポリマ・バッテリー向けの統合型 800mA リニア・チャージャです。このデバイスには、バッテリーを充電する電源出力が 1 つあります。バッテリーと並列にシステム負荷を接続できますが、平均システム負荷によって安全タイマ設定時間内でのバッテリーのフル充電を妨げないという条件があります。システム負荷をバッテリーと並列に接続する場合、充電電流はシステムとバッテリーの間で共有されます。

このデバイスは、リチウムイオン / リチウムポリマ・バッテリーを充電するための 3 つのフェーズを備えています。完全に放電されたバッテリーを回復するプリチャージ、大量の電荷を供給する定電流の高速充電、最大容量に達するための電圧レギュレーションです。

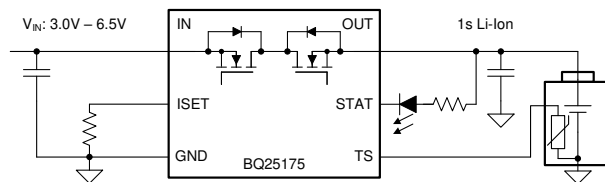
すべての充電フェーズで、内部の制御ループが IC の接合部温度を監視し、内部温度スレッシュホールド T_{REG} を超えた場合には充電電流を減少させます。

充電器の電源段と充電電流センス機能がすべて統合されています。この充電器には、高精度の電流および電圧レギュレーション・ループ、充電ステータスの表示、および充電自動終了の機能があります。高速充電電流の値は、外付けの抵抗によりプログラム可能です。プリチャージおよび終了電流スレッシュホールドは、高速充電電流の設定に従います。

製品情報

部品番号 ⁽¹⁾	パッケージ	本体サイズ (公称)
BQ25175	DSBGA (6)	0.8mm × 1.25mm

- (1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。



概略回路図



Table of Contents

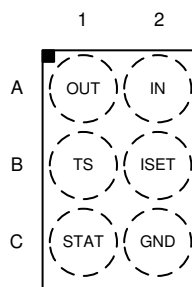
1 特長	1	7.4 Device Functional Modes.....	16
2 アプリケーション	1	8 Application and Implementation	18
3 概要	1	8.1 Application Information.....	18
4 Revision History	2	8.2 Typical Applications.....	18
5 Pin Configuration and Functions	3	9 Power Supply Recommendations	22
6 Specifications	4	10 Layout	22
6.1 Absolute Maximum Ratings	4	10.1 Layout Guidelines.....	22
6.2 ESD Ratings	4	10.2 Layout Example.....	22
6.3 Recommended Operating Conditions	4	11 Device and Documentation Support	23
6.4 Thermal Information	5	11.1 Device Support.....	23
6.5 Electrical Characteristics	6	11.2 Receiving Notification of Documentation Updates..	23
6.6 Timing Requirements	7	11.3 サポート・リソース.....	23
6.7 Typical Characteristics.....	8	11.4 Trademarks.....	23
7 Detailed Description	10	11.5 Electrostatic Discharge Caution.....	23
7.1 Overview.....	10	11.6 Glossary.....	23
7.2 Functional Block Diagram.....	12	12 Mechanical, Packaging, and Orderable Information	24
7.3 Feature Description.....	13		

4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision * (June 2021) to Revision A (September 2021)	Page
• 事前情報から量産データに変更.....	1

5 Pin Configuration and Functions



Top View = Xray through a soldered down part with A1 starting in upper left corner

图 5-1. YBG Package 6-Pin DSBGA Top View

表 5-1. Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
OUT	A1	P	Battery connection. System load may be connected in parallel to battery. Bypass OUT with at least a 1-μF capacitor to GND, place close to the IC.
IN	A2	P	Input power, connected to external DC supply. Bypass IN with at least a 1-μF capacitor to GND, place close to the IC.
TS	B1	I	Temperature qualification voltage input. Connect a negative temperature coefficient (NTC) thermistor directly from TS to GND (AT103-2 recommended). Charge suspends when $TS < V_{HOT}$ or $TS > V_{COLD}$. Charge at 20% of ISET when $V_{COLD} > TS > V_{COOL}$. If TS function is not needed, connect an external 10-kΩ resistor from this pin to GND. Pulling $TS < V_{TS_ENZ}$ disables the charger.
ISET	B2	I	Programs the device fast-charge current. An external resistor from ISET to GND defines fast charge current value. Expected range is 30 kΩ (10 mA) to 375 Ω (800 mA). $ICHG = K_{ISET} / R_{ISET}$. Precharge current is defined as 20% of ICHG. Termination current is defined as 10% of ICHG.
STAT	C1	O	Open drain charger status indication output. Connect to pull-up rail via 10-kΩ resistor. LOW indicates charge in progress. HIGH indicates charge complete or charge disabled. When a fault condition is detected, the STAT pin blinks at 1 Hz. If unsued, this pin can be left floating.
GND	C2	–	Ground pin

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
Voltage	IN	−0.3	30	V
Voltage	OUT	−0.3	13	V
Voltage	ISET, STAT, TS	−0.3	5.5	V
T _J	Junction temperature	−40	150	°C
T _{stg}	Storage temperature	−65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Rating* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Condition*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2500	V
		Charged device model (CDM), per ANSI/ESDA/JEDEC JS-002 ⁽²⁾	±1500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
 (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V _{IN}	Input voltage	3.0		6.6	V
V _{OUT}	Output voltage			4.35	V
I _{OUT}	Output current			0.8	A
T _J	Junction temperature	−40		125	°C
C _{IN}	IN capacitor	1			μF
C _{OUT}	OUT capacitor	1			μF
R _{ISET}	ISET resistor	0.375		30	kΩ
R _{TS}	TS thermistor resistor (recommend 103AT-2)		10		kΩ

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		BQ25175	UNIT
		YBG	
		6 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance (JEDEC ⁽¹⁾)	132.4	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	1.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	36.9	°C/W
Ψ_{JT}	Junction-to-top characterization parameter	0.4	°C/W
Ψ_{JB}	Junction-to-board characterization parameter	36.9	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

6.5 Electrical Characteristics

$3.0V < V_{IN} < V_{IN_OV}$ and $V_{IN} > V_{OUT} + V_{SLEEP}$, $T_J = -40^{\circ}C$ to $+125^{\circ}C$, and $T_J = 25^{\circ}C$ for typical values (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
QUIESCENT CURRENTS						
I_{Q_OUT}	Quiescent output current (OUT)	OUT = 4.2V, IN floating or IN = 0V - 5V, Charge Disabled, $T_J = 25^{\circ}C$		0.350	0.6	μA
		OUT = 4.2V, IN floating or IN = 0V - 5V, Charge Disabled, $T_J < 105^{\circ}C$		0.350	0.8	μA
$I_{SD_IN_TS}$	Shutdown input current (IN) with charge disabled via TS pin	IN = 5V, Charge Disabled ($V_{TS} < V_{TS_ENZ}$), no battery		80	110	μA
$I_{STANDBY_IN}$	Standby input current (IN) with charge terminated	IN = 5V, Charge Enabled, charge terminated		190		μA
I_{Q_IN}	Quiescent input current (IN)	IN = 5V, OUT = 3.8V, Charge Enabled, ICHG = 0A		0.45	0.6	mA
INPUT						
V_{IN_OP}	IN operating range		3.0		6.6	V
V_{IN_LOWV}	IN voltage to start charging	IN rising	3.05	3.09	3.15	V
V_{IN_LOWV}	IN voltage to stop charging	IN falling	2.80	2.95	3.10	V
V_{SLEEPZ}	Exit sleep mode threshold	IN rising, $V_{IN} - V_{OUT}$, OUT = 4V	95	135	175	mV
V_{SLEEP}	Sleep mode threshold hysteresis	IN falling, $V_{IN} - V_{OUT}$, OUT = 4V		80		mV
V_{IN_OV}	VIN overvoltage rising threshold	IN rising	6.60	6.75	6.90	V
V_{IN_OVZ}	VIN overvoltage falling threshold	IN falling		6.63		V
CONFIGURATION PINS SHORT/OPEN PROTECTION						
R_{ISET_SHORT}	Highest resistor value considered short	R_{ISET} below this at startup, charger does not initiate charge, power cycle or TS toggle to reset			350	Ω
BATTERY CHARGER						
V_{DO}	Dropout voltage ($V_{IN} - V_{OUT}$)	VIN = 4.4V, IOU = 300mA		425		mV
V_{REG_ACC}	OUT charge voltage accuracy	$T_J = 25^{\circ}C$	4.328	4.350	4.3721	V
V_{REG_ACC}		$T_J = -40^{\circ}C$ to $125^{\circ}C$	4.306	4.350	4.393	V
I_{CHG_RANGE}	Typical charge current regulation range	$V_{OUT} > V_{BAT_LOWV}$	10		800	mA
K_{ISET}	Charge current setting factor, $I_{CHG} = K_{ISET} / R_{ISET}$	$10mA < I_{CHG} < 800mA$	270	300	330	A Ω
I_{CHG_ACC}	Charge current accuracy	$R_{ISET} = 375\Omega$, OUT = 3.8V	720	800	880	mA
		$R_{ISET} = 600\Omega$, OUT = 3.8V	450	500	550	mA
		$R_{ISET} = 3.0k\Omega$, OUT = 3.8V	90	100	110	mA
		$R_{ISET} = 30k\Omega$, OUT = 3.8V	9	10	11	mA
I_{PRECHG}	Typical pre-charge current, as percentage of ICHG	$V_{OUT} < V_{BAT_LOWV}$		20		%
I_{PRECHG_ACC}	Precharge current accuracy	$R_{ISET} = 375\Omega$, OUT = 2.5V	144	160	176	mA
		$R_{ISET} = 600\Omega$, OUT = 2.5V	85	100	110	mA
		$R_{ISET} = 3.0k\Omega$, OUT = 2.5V	18	20	22	mA
		$R_{ISET} = 30k\Omega$, OUT = 2.5V	1.4	2	2.6	mA
I_{TERM}	Typical termination current, as percentage of ICHG	$V_{OUT} = V_{REG}$		10		%
I_{TERM_ACC}	Termination current accuracy	$R_{ISET} = 600\Omega$	45	50	55	mA
		$R_{ISET} = 3.0k\Omega$	8.5	10	11.5	mA
		$R_{ISET} = 30k\Omega$	0.4	1	1.6	mA

6.5 Electrical Characteristics (continued)

3.0V < V_{IN} < V_{IN_OV} and V_{IN} > V_{OUT} + V_{SLEEP}, T_J = -40°C to +125°C, and T_J = 25°C for typical values (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{BAT_SHORT}	Output (OUT) short circuit voltage rising threshold, for Li-Ion chemistry	OUT rising	2.1	2.2	2.3	V
V _{BAT_SHORT_HYS}	Output (OUT) short circuit voltage hysteresis	OUT falling		200		mV
I _{BAT_SHORT}	OUT short circuit charging current	V _{OUT} < V _{BAT_SHORT}	4	6	8	mA
V _{BAT_LOWV}	Pre-charge to fast-charge transition threshold, for Li-Ion chemistry	OUT rising	2.7	2.8	3.0	V
V _{BAT_LOWV_HYS}	Battery LOWV hysteresis	OUT falling		100		mV
V _{RECHG}	Battery recharge threshold for Li-Ion chemistry	OUT falling V _{REG_ACC} - V _{OUT}	75	100	125	mV
R _{ON}	Charging path FET on-resistance	V _{IN} = 4.4V, I _{OUT} = 300mA, T _J = 25°C		845	1000	mΩ
		V _{IN} = 4.4V, I _{OUT} = 300mA, T _J = -40 - 125°C		845	1450	mΩ
BATTERY CHARGER PROTECTION						
V _{OUT_OVP}	OUT overvoltage rising threshold	V _{OUT} rising, as percentage of V _{REG}	103	104	105	%
V _{OUT_OVP}	OUT overvoltage falling threshold	V _{OUT} falling, as percentage of V _{REG}	101	102	103	%
I _{OUT_OCP}	Output current limit threshold	I _{OUT} rising	0.9	1	1.1	A
TEMPERATURE REGULATION AND TEMPERATURE SHUTDOWN						
T _{REG}	Typical junction temperature regulation			125		°C
T _{SHUT}	Thermal shutdown rising threshold	Temperature increasing		150		°C
	Thermal shutdown falling threshold	Temperature decreasing		135		°C
BATTERY-PACK NTC MONITOR						
I _{TS_BIAS}	TS nominal bias current		36.5	38	39.5	μA
V _{COLD}	Cold temperature threshold	TS pin voltage rising (approx. 0°C)	0.99	1.04	1.09	V
	Cold temperature exit threshold	TS pin voltage falling (approx. 4°C)	0.83	0.88	0.93	V
V _{COOL}	Normal to low temperature charge; Charge current target reduced to 20% x ISET	TS pin voltage rising (approx. 10°C)	650	680	710	mV
	Low temperature to normal charge; Charge current target returns to ISET	TS pin voltage falling (approx. 13°C)	580	610	640	mV
V _{HOT}	Hot temperature threshold	TS pin voltage falling (approx. 45°C)	176	188	200	mV
	Hot temperature exit threshold	TS pin voltage rising (approx. 40°C)	208	220	232	mV
V _{TS_ENZ}	Charge Disable threshold. Crossing this threshold shall shutdown IC	TS pin voltage falling	40	50	60	mV
V _{TS_EN}	Charge Enable threshold. Crossing this threshold shall restart IC operation	TS pin voltage rising	65	75	85	mV
V _{TS_CLAMP}	TS maximum voltage clamp	TS pin open-circuit (float)	2.3	2.6	2.9	V
LOGIC OUTPUT PIN (STAT)						
V _{OL}	Output low threshold level	Sink current = 5mA			0.4	V
I _{OUT_BIAS}	High-level leakage current	Pull up rail 3.3V			1	μA

6.6 Timing Requirements

		MIN	NOM	MAX	UNIT
BATTERY CHARGER					
t _{TS_DUTY_ON}	TS turn-on time during TS duty cycle mode		100		ms
t _{TS_DUTY_OFF}	TS turn-off time during TS duty cycle mode		2		s

		MIN	NOM	MAX	UNIT
$t_{OUT_OCP_DGL}$	Deglitch time for I_{OUT_OCP} , I_{OUT} rising		100		μs
t_{PRECHG}	Pre-charge safety timer accuracy	28.5	30	31.5	min
t_{SAFETY}	Fast-charge safety timer accuracy	9.5	10	10.5	hr

6.7 Typical Characteristics

$C_{IN} = 1 \mu F$, $C_{OUT} = 1 \mu F$

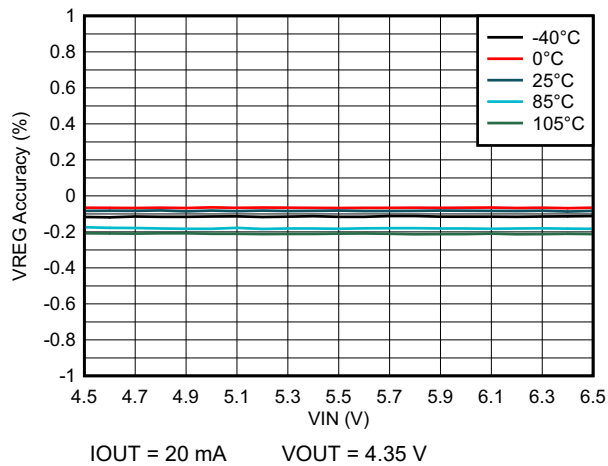


Figure 6-1. Line Regulation

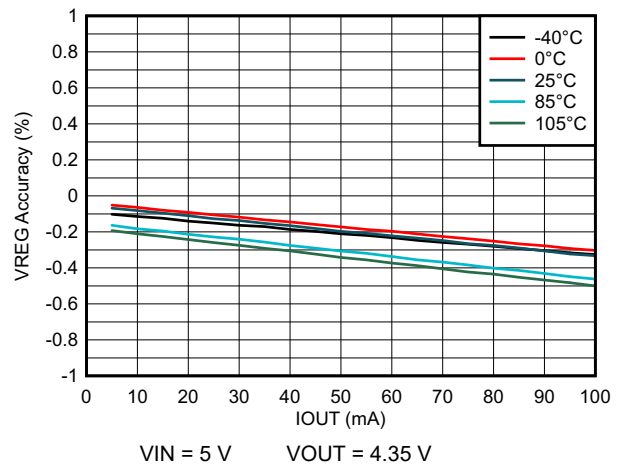


Figure 6-2. Load Regulation

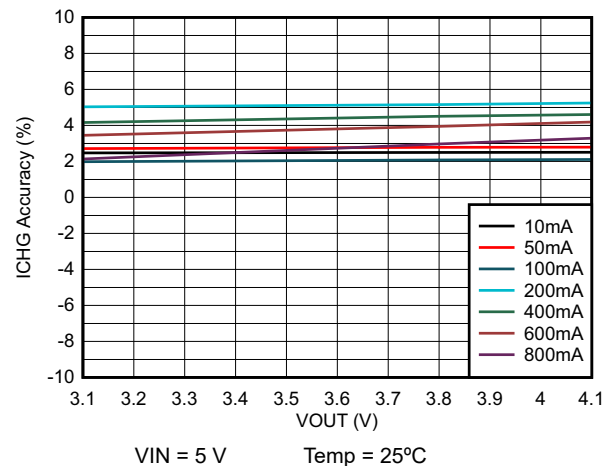


Figure 6-3. ICHG Accuracy vs. V_{OUT}

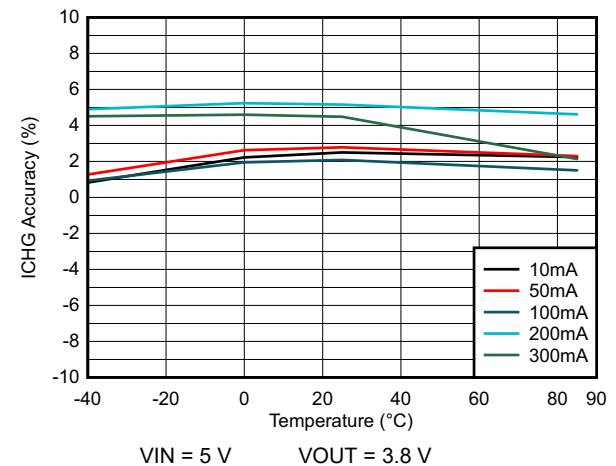
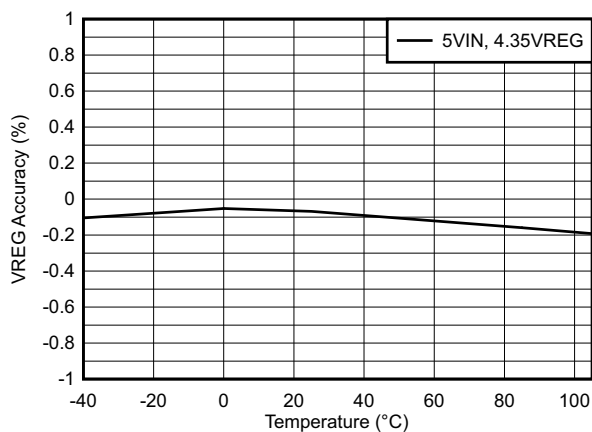


Figure 6-4. ICHG Accuracy vs. Temperature

6.7 Typical Characteristics (continued)

$C_{IN} = 1 \mu F$, $C_{OUT} = 1 \mu F$



$I_{OUT} = 10 \text{ mA}$

FIG 6-5. VSET Accuracy vs. Temperature

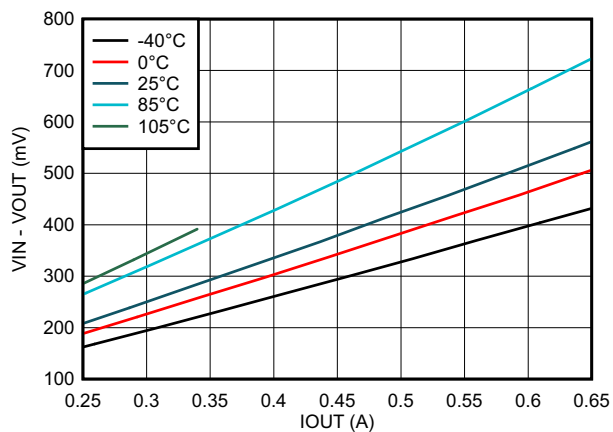
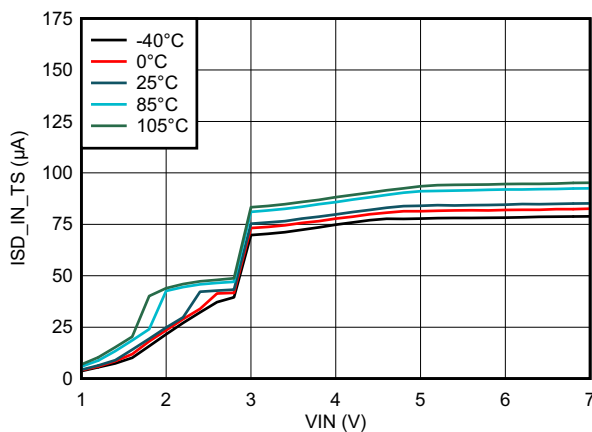


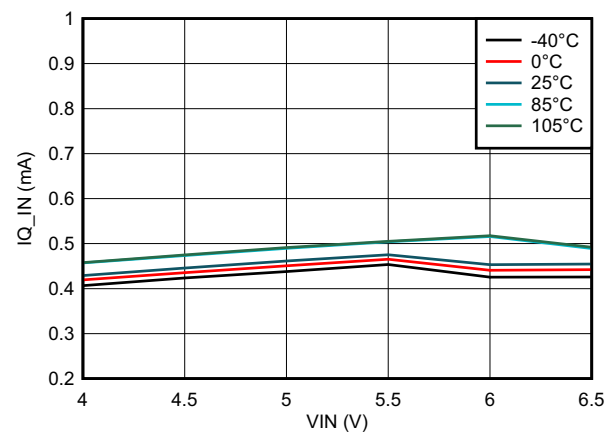
FIG 6-6. Dropout Voltage vs. Output Current



TS Pin = LOW

$V_{OUT} = 0 \text{ V}$

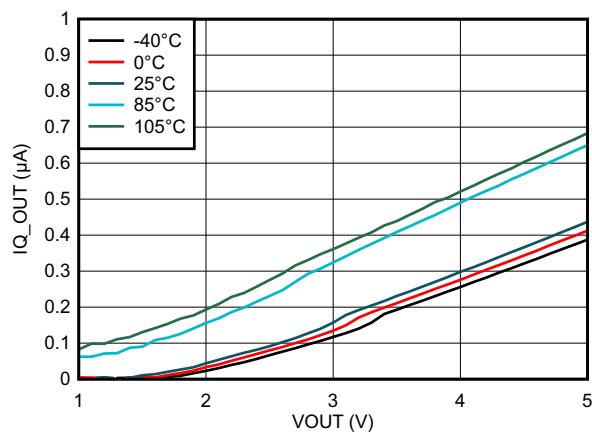
FIG 6-7. Input Shutdown Current vs. Input Voltage



$I_{CHG} = 0 \text{ A}$

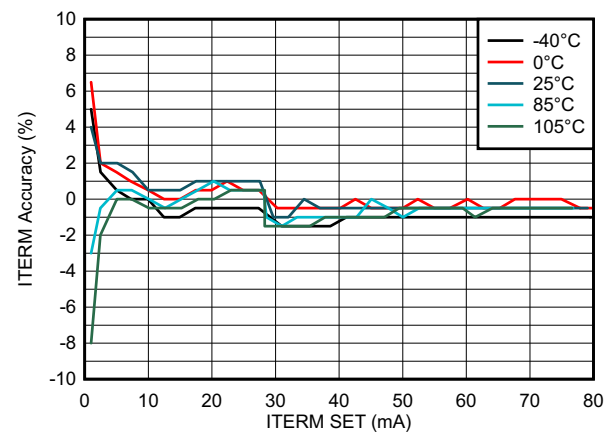
$V_{OUT} = 0 \text{ V}$

FIG 6-8. Input Quiescent Current vs. Input Voltage



$V_{IN} = 0 \text{ V}$

FIG 6-9. Output Quiescent Current vs. Output Voltage



$V_{IN} = 5 \text{ V}$

$V_{OUT} = 4.35 \text{ V}$

FIG 6-10. Termination Current Accuracy vs. Termination Current Setting

7 Detailed Description

7.1 Overview

The BQ25175 is an integrated 800-mA linear charger for 1-cell Li-Ion/Li-Poly batteries. The device has a single power output that charges the battery. The system load can be placed in parallel with the battery, as long as the average system load does not prevent the battery from charging fully within the safety timer duration. When the system load is placed in parallel with the battery, the input current is shared between the system and the battery.

The device has three phases for charging a Li-Ion/Li-Poly battery: precharge to recover a fully discharged battery, fast-charge constant current to supply the bulk of the charge, and voltage regulation to reach full capacity.

The charger includes flexibility in programming of the fast-charge current. This charger is designed to work with a standard USB connection or dedicated charging adapter (DC output).

The charger also comes with a full set of safety features: battery temperature monitoring, overvoltage protection, charge safety timers, and configuration pin (ISET) short and open protection. All of these features and more are described in detail below.

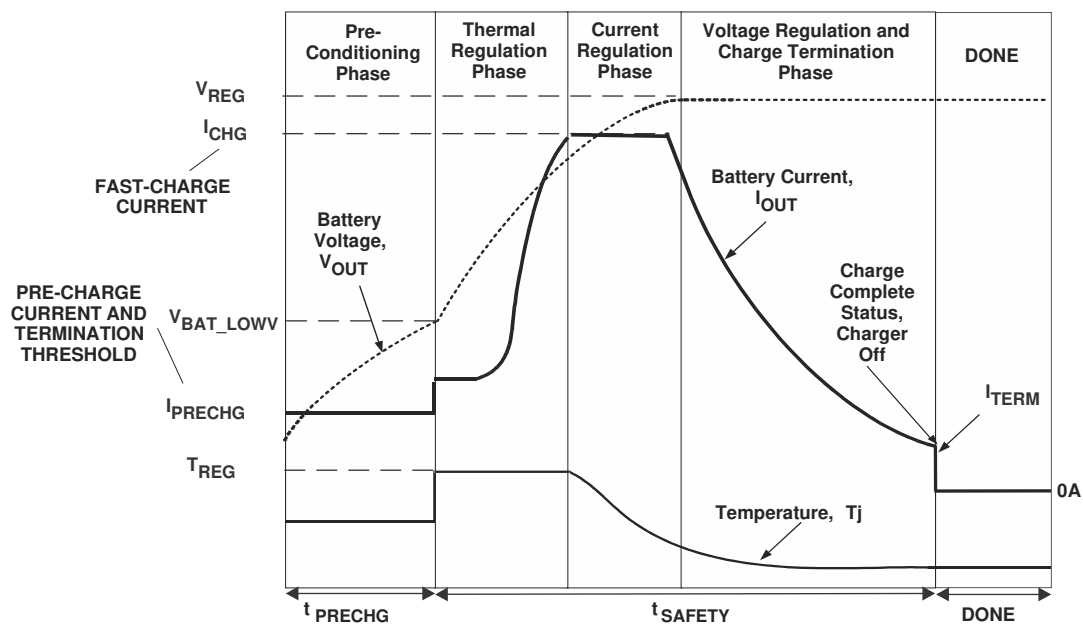
The charger is designed for a single path from the input to the output to charge the battery. Upon application of a valid input power source, the configuration pins are checked for short/open circuit.

If the battery voltage is below the V_{BAT_LOWV} threshold, the battery is considered discharged and a preconditioning cycle begins. The amount of precharge current is 20% of the programmed fast-charge current via the ISET pin. The t_{PRECHG} safety timer is active, and stops charging after expiration if battery voltage fails to rise above V_{BAT_LOWV} .

Once the battery has charged to the V_{BAT_LOWV} threshold, Fast Charge Mode is initiated, applying the fast charge current and starting the t_{SAFETY} timer. The fast charge constant current is programmed using the ISET pin. The constant current phase provides the bulk of the charge. Power dissipation in the IC is greatest in fast charge with a lower battery voltage. If the IC temperature reaches T_{REG} , the IC enters thermal regulation, slows the timer clock by half, and reduces the charge current as needed to keep the temperature from rising any further.  7-1 shows the typical lithium battery charging profile with thermal regulation. Under normal operating conditions, the IC junction temperature is less than T_{REG} and thermal regulation is not entered.

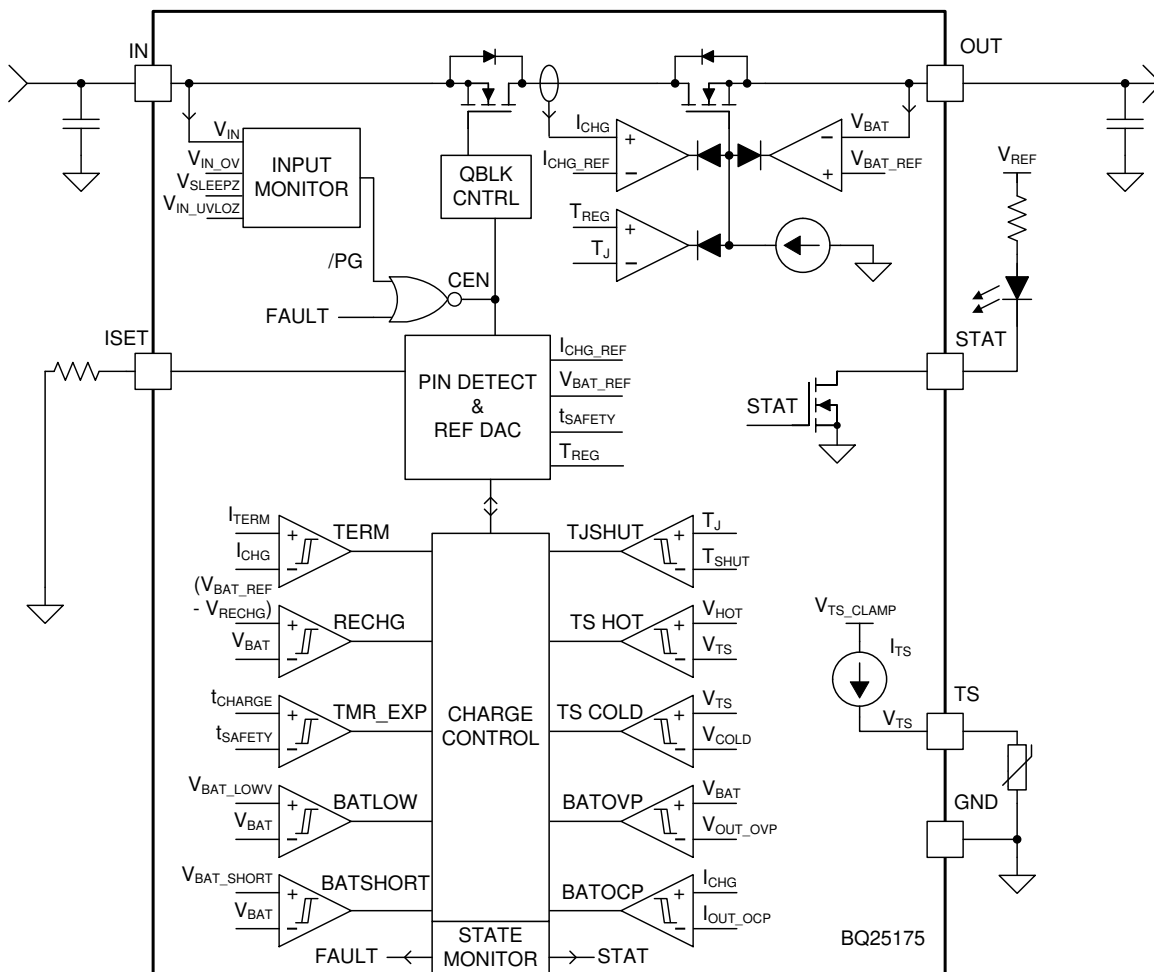
Once the battery has charged to the regulation voltage, the voltage loop takes control and holds the battery at the regulation voltage until the current tapers to the termination threshold. The termination threshold is 10% of the programmed fast-charge current.

Further details are described in [セクション 7.3](#).



7-1. Lithium-Ion Battery Charging Profile with Thermal Regulation

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 Device Power Up from Input Source

When an input source is plugged in and charge is enabled, the device checks the input source voltage to turn on all the bias circuits. It detects and sets the charge current and charge voltage limits before the linear regulator is started. The power up sequence from input source is as listed:

1. ISET pin detection
2. Charger power up

7.3.1.1 ISET Pin Detection

After a valid VIN is plugged in, the device checks the resistor on the ISET pin for a short circuit ($R_{ISET} < R_{ISET_SHORT}$). If a short condition is detected, the charger remains in the FAULT state until the input or TS pin is toggled. If the ISET pin is open-circuit, the charger proceeds through pin detection and starts the charger with no charge current. This pin is monitored while charging and changes in R_{ISET} while the charger is operating will immediately translate to changes in charge current.

An external pulldown resistor ($\pm 1\%$ or better is recommended to minimize charge current error) from the ISET pin to GND sets the charge current as:

$$I_{CHG} = \frac{K_{ISET}}{R_{ISET}} \quad (1)$$

where:

- I_{CHG} is the desired fast-charge current
- K_{ISET} is a gain factor found in the electrical specifications
- R_{ISET} is the pulldown resistor from the ISET pin to GND

For charge currents below 50 mA, an extra RC circuit is recommended on ISET to achieve a more stable current signal. For greater accuracy at lower currents, part of the current-sensing FET is disabled to give better resolution.

7.3.1.2 Charger Power Up

After ISET pin resistor values have been validated, the device proceeds to enable the charger. The device automatically begins operation at the correct stage of battery charging depending on the OUT voltage.

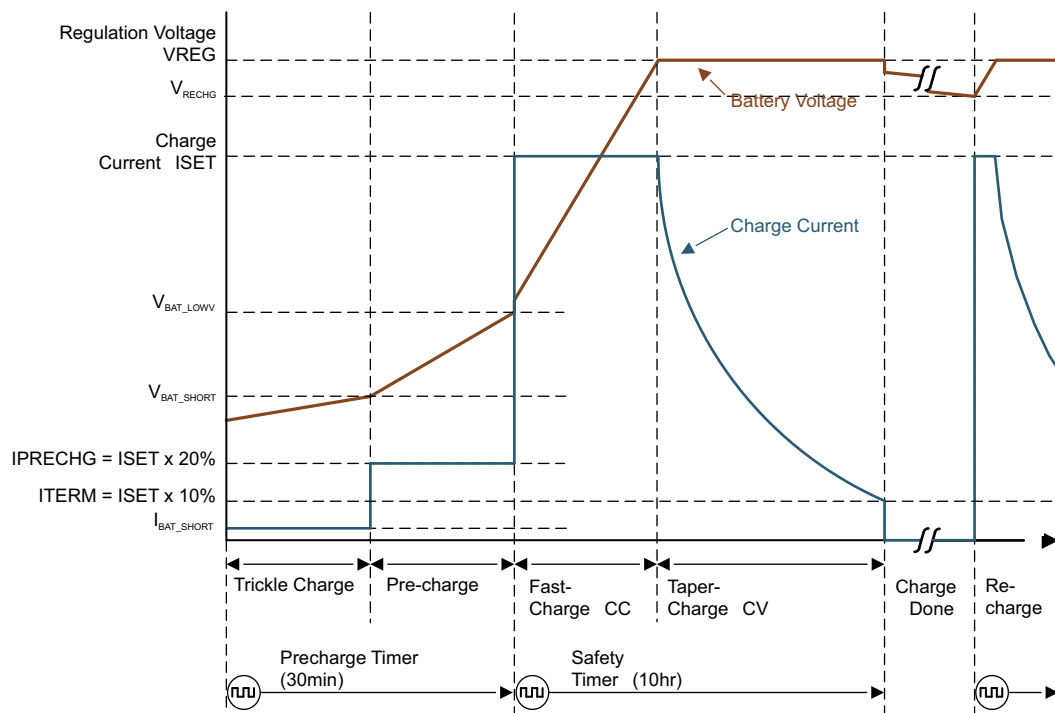
7.3.2 Battery Charging Features

When charge is enabled, the device automatically completes a charging cycle according to the setting on the ISET pin without any intervention. The lithium-based charging cycle is automatically terminated when the charging current is below termination threshold, charge voltage is above recharge threshold, and device is not in thermal regulation (TREG). When a full battery is discharged below the recharge threshold (V_{RECHG}), the device automatically starts a new charging cycle. After charge is done, toggling the input supply or the TS pin can initiate a new charging cycle.

7.3.2.1 Lithium-Ion Battery Charging Profile

The device charges a lithium based battery in four phases: trickle charge, precharge, constant current, and constant voltage. At the beginning of a charging cycle, the device checks the battery voltage and regulates current and voltage accordingly.

If the charger is in thermal regulation during charging, the actual charging current is less than the programmed value. In this case, termination is temporarily disabled and the charging safety timer is counted at half the clock rate. For more information, refer to [セクション 7.3.2.3](#).



7-2. Battery Charging Profile

7.3.2.2 Charge Termination and Battery Recharge

The device terminates a charge cycle when the OUT pin voltage is above the recharge threshold (V_{RECHG}) and the current is below the termination threshold (I_{TERM}). Termination is temporarily disabled when the charger device is in thermal regulation. After charge termination is detected, the linear regulator turns off and the device enters the STANDBY state. Once the OUT pin drops below the V_{RECHG} threshold, a new charge cycle is automatically initiated.

7.3.2.3 Charging Safety Timers

The device has built-in safety timers to prevent an extended charging cycle due to abnormal battery conditions. The precharge timer is fixed at 30 minutes. The fast-charge safety timer is fixed at 10 hours. When the safety timer expires, the charge cycle ends. A toggle on the input supply or TS pin is required to restart a charge cycle after the safety timer has expired.

During thermal regulation, the safety timer counts at half the clock rate as the actual charge current is likely to be below the I_{SET} setting. For example, if the charger is in thermal regulation throughout the whole charging cycle and the safety timer is 10 hours, then the timer will expire in 20 hours.

During faults which disable charging, such as VIN OVP, BAT OVP, TSHUT, or TS faults, the timer is suspended. Once the fault goes away, charging and the safety timer resume. If the charging cycle is stopped and started again, the timer gets reset (toggle of the TS pin restarts the timer).

The safety timer restarts counting for the following events:

1. Charging cycle stop and restart (toggle TS pin, charged battery falls below recharge threshold, or toggle input supply)
2. OUT pin voltage crosses the V_{BAT_LOWV} threshold in either direction

The precharge safety timer (fixed counter that runs when $V_{OUT} < V_{BAT_LOWV}$), follows the same rules as the fast-charge safety timer in terms of getting suspended, reset, and counting at half-rate.

7.3.2.4 Battery Cold, Hot Temperature Qualification (TS Pin)

While charging, the device continuously monitors battery temperature by sensing the voltage at the TS pin. A negative temperature coefficient (NTC) thermistor should be connected between the TS and GND pins (recommend: 103AT-2). If temperature sensing is not required in the application, connect a fixed 10-kΩ resistor from TS to GND to allow normal operation. Battery charging is allowed when the TS pin voltage falls between the V_{COLD} and V_{HOT} thresholds (typically 0°C to 45°C). Charging current is reduced to 20% of the programmed ISET value when $V_{COLD} > TS > V_{COOL}$ (typically 0°C to 10°C). The charging profile can be seen in [Figure 7-3](#).

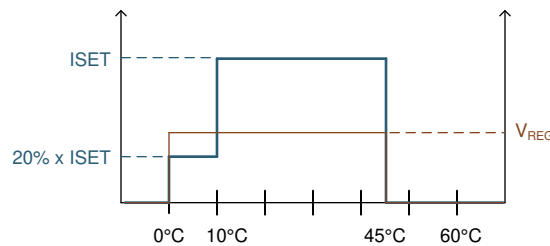


Figure 7-3. BQ25175 Charging Profile

If the TS pin indicates battery temperature is outside this range, the device stops charging, enters the STANDBY state, and blinks the STAT pin. Once battery temperature returns to normal conditions, charging resumes automatically.

In addition to battery temperature sensing, the TS pin can be used to disable the charger at any time by pulling TS voltage below V_{TS_ENZ} . The device disables the charger and consumes $I_{SD_IN_TS}$ from the input supply. In order to minimize quiescent current, the TS current source (I_{TS_BIAS}) is duty-cycled, with an on time of $t_{TS_DUTY_ON}$ and an off time of $t_{TS_DUTY_OFF}$. After the TS pin pulldown is released, the device may take up to $t_{TS_DUTY_OFF}$ to turn the I_{TS_BIAS} back on. After the source is turned on, the TS pin voltage will go above V_{TS_EN} , and re-enable the charger operation. The device treats this TS pin toggle as an input supply toggle, triggering a device power up from input source (see [Section 7.3.1](#)).

7.3.3 Status Outputs (STAT)

7.3.3.1 Charging Status Indicator (STAT)

The device indicates the charging state on the open-drain STAT pin. This pin can drive an LED.

Table 7-1. STAT Pin State

CHARGING STATE	STAT PIN STATE
Charge completed, charger in Sleep mode or charge disabled ($V_{TS} < V_{TS_ENZ}$)	HIGH
Charge in progress (including automatic recharge)	LOW
Fault (VIN OVP, BAT OVP, BAT OCP, TS HOT, TS COLD, TMR_EXP, or ISET pin short)	BLINK at 1 Hz

7.3.4 Protection Features

The device closely monitors input and output voltages, as well as internal FET current and temperature for safe linear regulator operation.

7.3.4.1 Input Overvoltage Protection (VIN OVP)

If the voltage at the IN pin exceeds V_{IN_OV} , the device turns off after a deglitch, $t_{VIN_OV_DGL}$. The safety timer suspends counting and the device enters Standby mode. Once the IN voltage recovers to a normal level, the charge cycle and the safety timer automatically resume operation.

7.3.4.2 Output Overvoltage Protection (BAT OVP)

If the voltage at the OUT pin exceeds V_{OUT_OVP} , the device immediately stops charging. The safety timer suspends counting and the device enters Standby mode. Once the OUT voltage recovers to a normal level, the charge cycle and the safety timer resume operation.

7.3.4.3 Output Overcurrent Protection (BAT OCP)

During normal operation, the OUT current should be regulated to the ISET programmed value. However, if a short circuit occurs on the ISET pin, the OUT current may rise to an unintended level. If the current at the OUT pin exceeds I_{OUT_OCP} , the device turns off after a deglitch, $t_{OUT_OCP_DGL}$. The safety timer resets the count, and the device remains latched off. An input supply or TS pin toggle is required to restart operation.

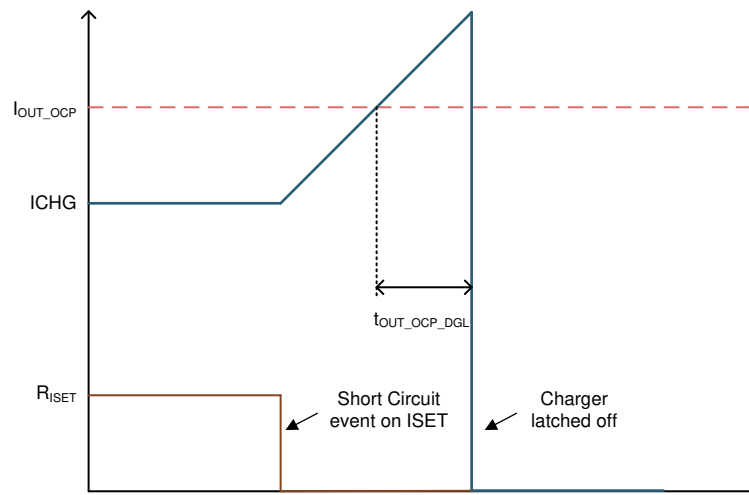


图 7-4. Overcurrent Protection

7.3.4.4 Thermal Regulation and Thermal Shutdown (TREG and TSHUT)

The device monitors its internal junction temperature (T_J) to avoid overheating and to limit the IC surface temperature. When the internal junction temperature exceeds the thermal regulation limit, the device automatically reduces the charge current to maintain the junction temperature at the thermal regulation limit (TREG). During thermal regulation, the actual charging current is usually below the programmed value on the ISET pin.

Therefore, the termination comparator for the Lithium-Ion battery is disabled, and the safety timer runs at half the clock rate.

Additionally, the device has thermal shutdown to turn off the linear regulator when the IC junction temperature exceeds the TSHUT threshold. The charger resumes operation when the IC die temperature decreases below the TSHUT falling threshold.

7.4 Device Functional Modes

7.4.1 Shutdown or Undervoltage Lockout (UVLO)

The device is in the shutdown state if the IN pin voltage is less than V_{IN_LOWV} or the TS pin is below V_{TS_ENZ} . The internal circuitry is powered down, all the pins are high impedance, and the device draws $I_{SD_IN_TS}$ from the input supply. Once the IN voltage rises above the V_{IN_LOW} threshold and the TS pin is above V_{TS_EN} , the IC enters Sleep mode or Active mode depending on the OUT pin voltage.

7.4.2 Sleep Mode

The device is in Sleep mode when $V_{IN_LOWV} < V_{IN} < V_{OUT} + V_{SLEEPZ}$. The device waits for the input voltage to rise above $V_{OUT} + V_{SLEEPZ}$ to start operation.

7.4.3 Active Mode

The device is powered up and charges the battery when the TS pin is above V_{TS_ENZ} and the IN voltage ramps above both V_{IN_LOWV} and $V_{OUT} + V_{SLEEPZ}$. The device draws I_{Q_IN} from the supply to bias the internal circuitry. For details on the device power-up sequence, refer to [セクション 7.3.1](#).

7.4.3.1 Standby Mode

The device is in Standby mode if a valid input supply is present and charge is terminated or if a recoverable fault is detected. The internal circuitry is partially biased, and the device continues to monitor for either VOUT to drop below V_{RECHG} or the recoverable fault to be removed.

7.4.4 Fault Mode

The fault conditions are categorized into recoverable and nonrecoverable as follows:

- Recoverable, from which the device should automatically recover once the fault condition is removed:
 - VIN OVP
 - BAT OVP
 - TS HOT
 - TS COLD
- Nonrecoverable, requiring pin or input supply toggle to resume operation:
 - BAT OCP
 - ISET pin short detected

8 Application and Implementation

Note

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくことになります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

8.1 Application Information

A typical application consists of the device configured as a standalone battery charger for single-cell Li-Ion or Li-Poly chemistries. The charge current is configured using a pulldown resistor on the ISET pin. A battery thermistor can be connected to the TS pin to allow the device to monitor battery temperature and control charging. Pulling the TS pin below V_{TS_ENZ} disables the charging function. Charger status is reported via the STAT pin.

8.2 Typical Applications

8.2.1 Li-Ion Charger Design Example

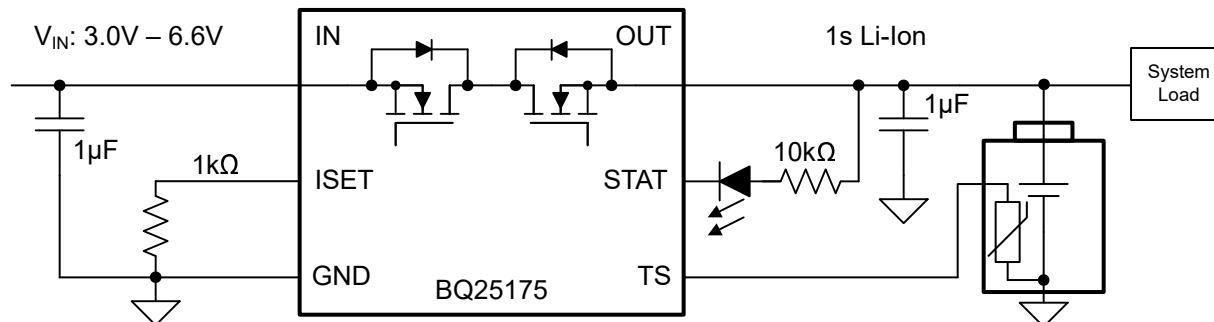


図 8-1. BQ25175 Typical Application for 1s Li-Ion Charging at 100 mA

8.2.1.1 Design Requirements

- Input supply up-to 6.6 V
- Battery is 1-cell Li-ion
- Fast charge current: $I_{CHG} = 300 \text{ mA}$
- Charge voltage: $V_{REG} = 4.35 \text{ V}$
- Termination current: $I_{TERM} = 10\% \text{ of } I_{CHG} \text{ or } 30 \text{ mA}$
- Precharge current: $I_{PRECHG} = 20\% \text{ of } I_{CHG} \text{ or } 60 \text{ mA}$
- TS – Battery temperature sense = 10-kΩ NTC (103AT)
 - Charging allowed between battery temperatures of 0°C to 45°C, with charge current reduction ($I_{OUT} = 20\% \times I_{SET}$) between 0°C and 10°C
- TS pin can be pulled low to disable charging or left floating to enable charging

8.2.1.2 Detailed Design Procedure

Regulation voltage is fixed to 4.35 V, input voltage is 5 V, and charge current is programmed via the ISET pin to 300 mA.

$$R_{ISET} = [K_{ISET} / I_{CHG}]$$

from the Electrical Characteristics table $K_{ISET} = 300 \text{ A}\Omega$

$$R_{ISET} = [300 \text{ A}\Omega / 0.3 \text{ A}] = 1000 \Omega$$

8.2.1.2.1 TS Function

Use a 10-kΩ NTC thermistor in the battery pack (recommend: 103AT-2). The V_{COLD} and V_{HOT} thresholds in this data sheet are designed to meet a charging window between 0°C and 45°C for a 10-kΩ NTC with $\beta = 3435 \text{ K}$. To

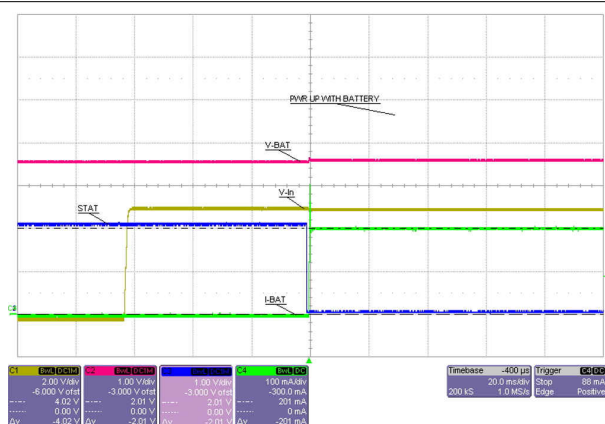
disable the TS sense function, use a fixed 10-k Ω resistor between the TS pin and GND. The TS pin can be pulled down to disable charging.

BQ25175

JAJS15A – JUNE 2021 – REVISED SEPTEMBER 2021

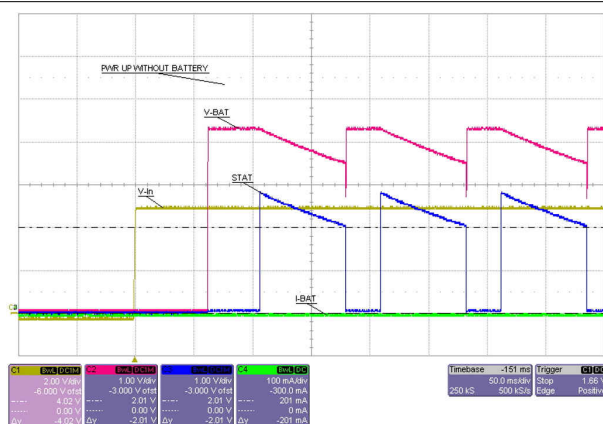
8.2.1.3 Application Curves

$C_{IN} = 1 \mu F$, $C_{OUT} = 1 \mu F$, $V_{IN} = 5 V$, $I_{CHG} = 200 mA$ (unless otherwise specified)



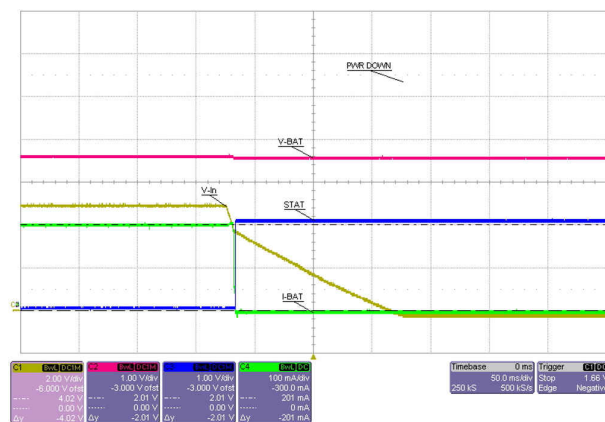
$R_{SET} = 1.2 k\Omega$

8-2. Power Up with Battery



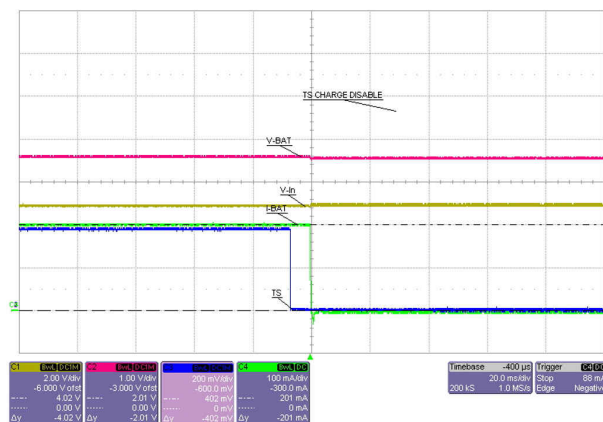
$R_{SET} = 1.2 k\Omega$ OUT = open-circuit

8-3. Power Up without Battery



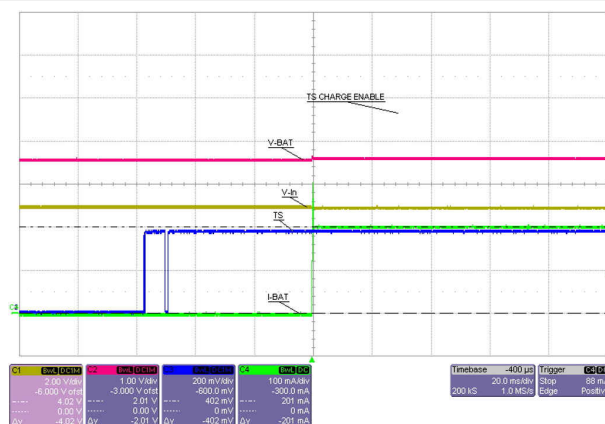
$V_{IN} = 5V \rightarrow 0V$

8-4. Power Down



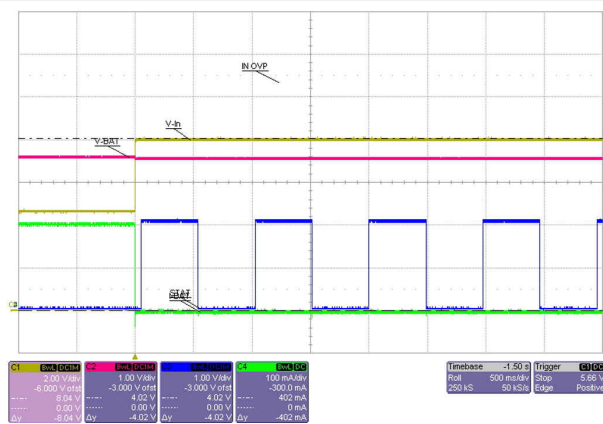
TS pulled LOW

8-5. Charge Disable

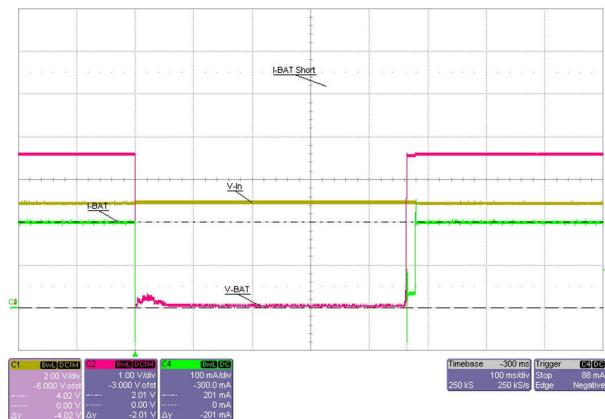


TS pin released

8-6. Charge Enable

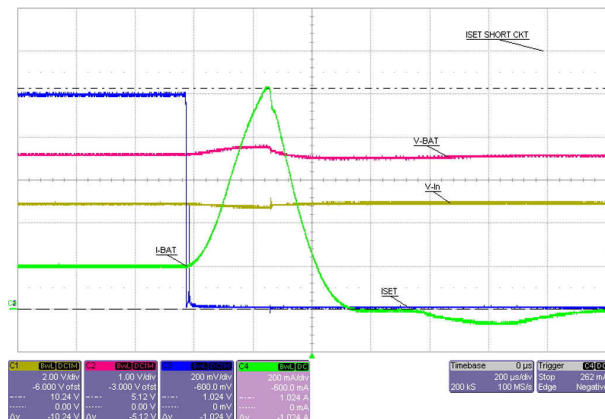


8-7. IN OVP Response



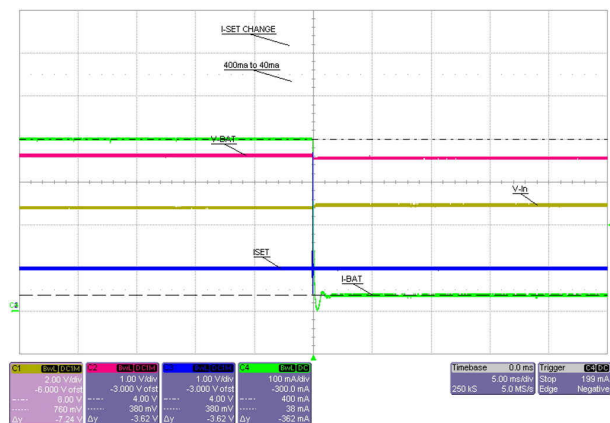
$V_{OUT} = V_{REG} = 3.5 \text{ V} \rightarrow 0 \text{ V}$

8-8. OUT Short-Circuit Response



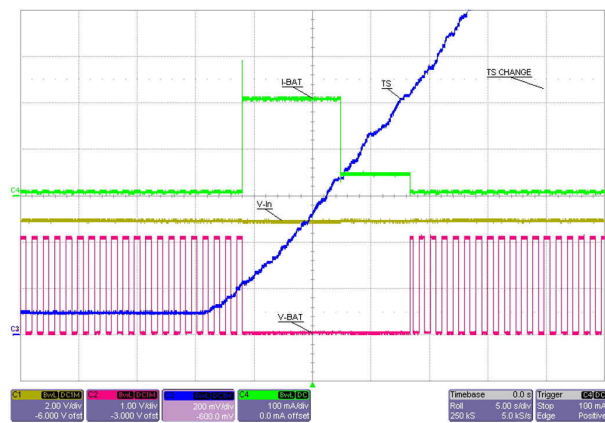
$I_{SET} = 1.5 \text{ k}\Omega \rightarrow 0 \Omega$

8-9. ISET Short-Circuit Response



$I_{SET} = 400 \text{ mA} \rightarrow 40 \text{ mA}$

8-10. ISET Change Response



8-11. TS Change Response

9 Power Supply Recommendations

The device is designed to operate from an input voltage supply range between 3.0 V and 6.6 V (up to 30 V tolerant) and current capability of at least the maximum designed charge current. If located more than a few inches from the IN and GND pins, a larger capacitor is recommended.

10 Layout

10.1 Layout Guidelines

To obtain optimal performance, the decoupling capacitor from the IN pin to the GND pin and the output filter capacitor from the OUT pin to the GND pin should be placed as close as possible to the device, with short trace runs to both IN, OUT, and GND.

- All low-current GND connections should be kept separate from the high-current charge or discharge paths from the battery. Use a single-point ground technique incorporating both the small signal ground path and the power ground path.
- The high current charge paths into the IN pin and from the OUT pin must be sized appropriately for the maximum charge current in order to avoid voltage drops in these traces.

10.2 Layout Example

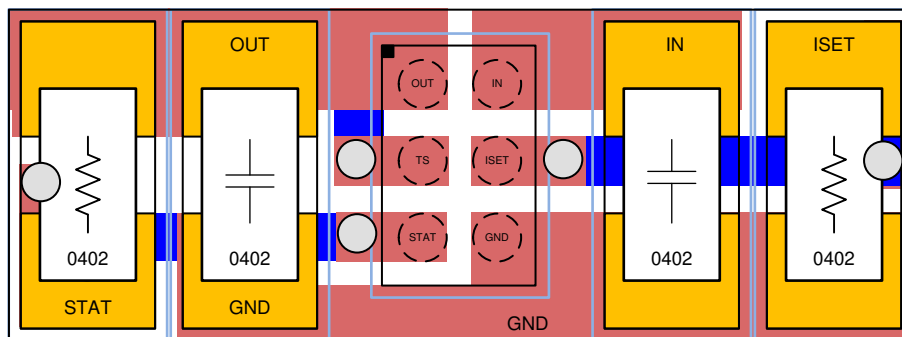


FIG 10-1. BQ25175 Board Layout Example

11 Device and Documentation Support

11.1 Device Support

11.1.1 Third-Party Products Disclaimer

TI'S PUBLICATION OF INFORMATION REGARDING THIRD-PARTY PRODUCTS OR SERVICES DOES NOT CONSTITUTE AN ENDORSEMENT REGARDING THE SUITABILITY OF SUCH PRODUCTS OR SERVICES OR A WARRANTY, REPRESENTATION OR ENDORSEMENT OF SUCH PRODUCTS OR SERVICES, EITHER ALONE OR IN COMBINATION WITH ANY TI PRODUCT OR SERVICE.

11.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on [ti.com](https://www.ti.com). Click on *Subscribe to updates* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.3 サポート・リソース

TI E2E™ サポート・フォーラムは、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

リンクされているコンテンツは、該当する貢献者により、現状のまま提供されるものです。これらは TI の仕様を構成するものではなく、必ずしも TI の見解を反映したものではありません。TI の [使用条件](#)を参照してください。

11.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

11.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.6 Glossary

TI Glossary This glossary lists and explains terms, acronyms, and definitions.

12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
BQ25175YBGR	Active	Production	DSBGA (YBG) 6	3000 LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	B75
BQ25175YBGR.A	Active	Production	DSBGA (YBG) 6	3000 LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	B75

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

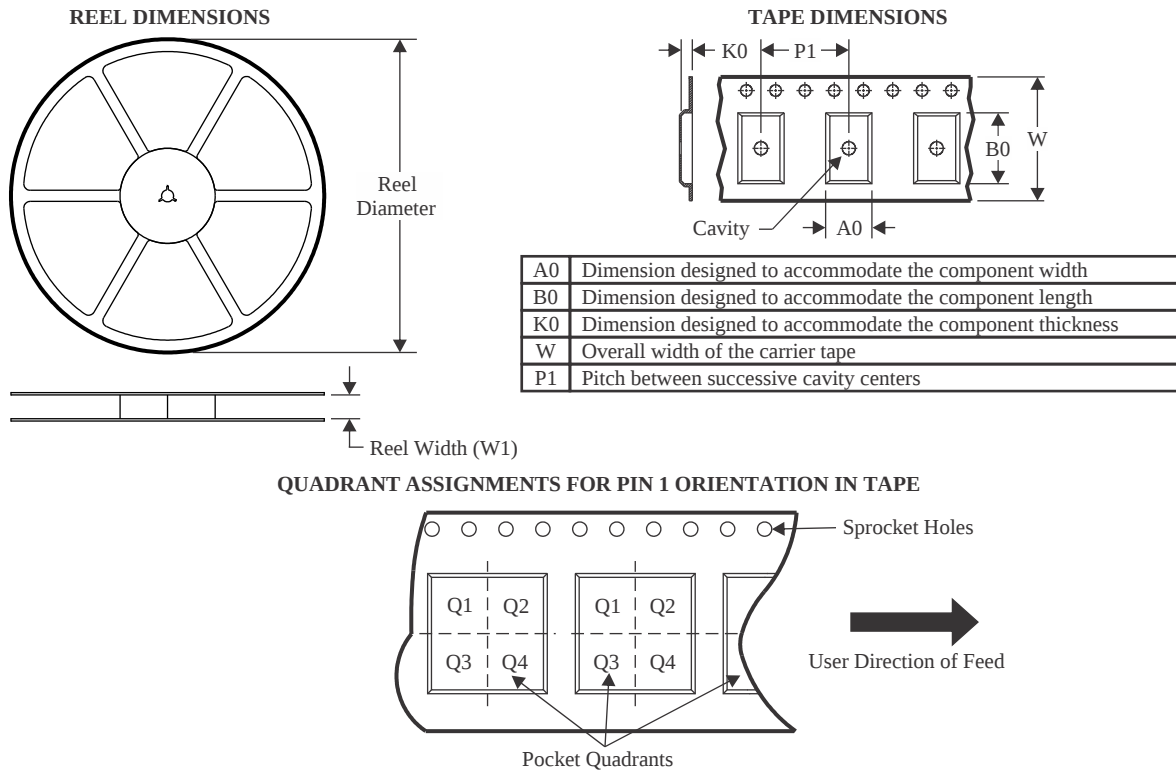
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ25175YBGR	DSBGA	YBG	6	3000	180.0	8.4	0.92	1.26	0.55	2.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BQ25175YBGR	DSBGA	YBG	6	3000	182.0	182.0	20.0

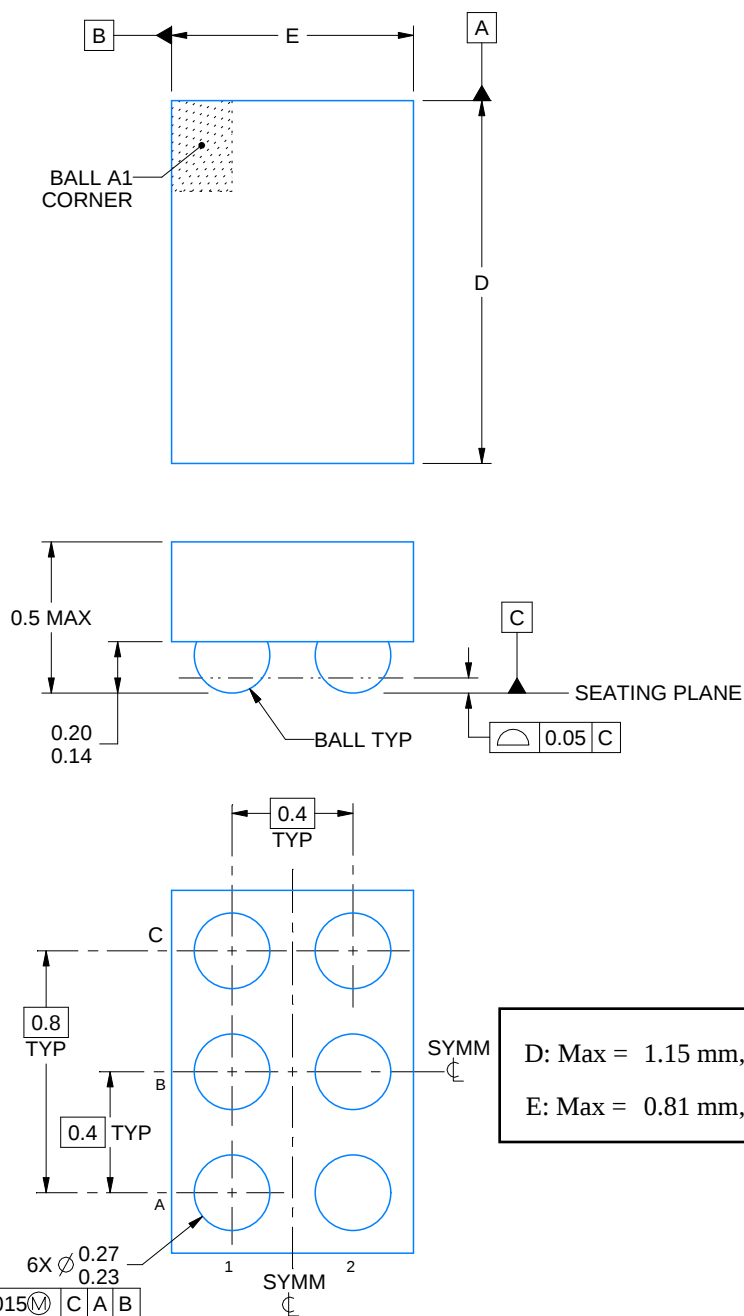
YBG0006



PACKAGE OUTLINE

DSBGA - 0.5 mm max height

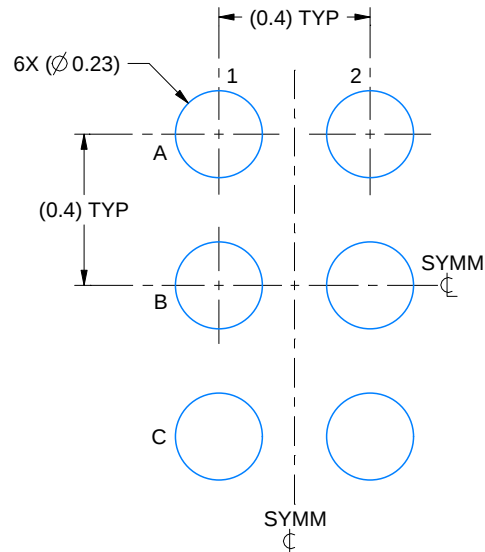
DIE SIZE BALL GRID ARRAY



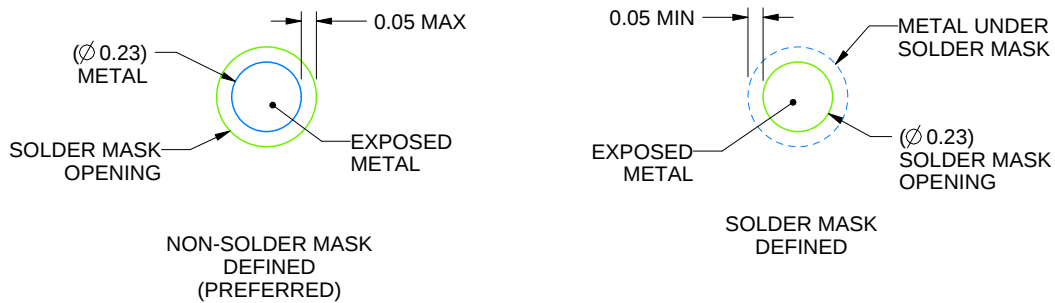
4224328/A 05/2018

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 50X

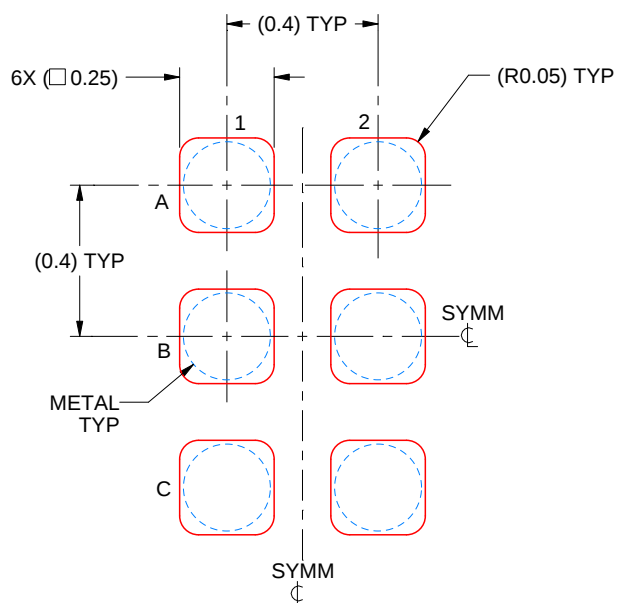


SOLDER MASK DETAILS
NOT TO SCALE

4224328/A 05/2018

NOTES: (continued)

- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SNVA009 (www.ti.com/lit/snva009).



SOLDER PASTE EXAMPLE
 BASED ON 0.1 mm THICK STENCIL
 SCALE: 50X

4224328/A 05/2018

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

重要なお知らせと免責事項

テキサス・インスツルメンツは、技術データと信頼性データ (データシートを含みます)、設計リソース (リファレンス デザインを含みます)、アプリケーションや設計に関する各種アドバイス、Web ツール、安全性情報、その他のリソースを、欠陥が存在する可能性のある「現状のまま」提供しており、商品性および特定目的に対する適合性の黙示保証、第三者の知的財産権の非侵害保証を含むいかなる保証も、明示的または黙示的にかかわらず拒否します。

これらのリソースは、テキサス・インスツルメンツ製品を使用する設計の経験を積んだ開発者への提供を意図したものです。(1) お客様のアプリケーションに適したテキサス・インスツルメンツ製品の選定、(2) お客様のアプリケーションの設計、検証、試験、(3) お客様のアプリケーションに該当する各種規格や、その他のあらゆる安全性、セキュリティ、規制、または他の要件への確実な適合に関する責任を、お客様のみが単独で負うものとします。

上記の各種リソースは、予告なく変更される可能性があります。これらのリソースは、リソースで説明されているテキサス・インスツルメンツ製品を使用するアプリケーションの開発の目的でのみ、テキサス・インスツルメンツはその使用をお客様に許諾します。これらのリソースに関して、他の目的で複製することや掲載することは禁止されています。テキサス・インスツルメンツや第三者の知的財産権のライセンスが付与されている訳ではありません。お客様は、これらのリソースを自身で使用した結果発生するあらゆる申し立て、損害、費用、損失、責任について、テキサス・インスツルメンツおよびその代理人を完全に補償するものとし、テキサス・インスツルメンツは一切の責任を拒否します。

テキサス・インスツルメンツの製品は、[テキサス・インスツルメンツの販売条件](#)、または [ti.com](https://www.ti.com) やかかるテキサス・インスツルメンツ製品の関連資料などのいずれかを通じて提供する適用可能な条項の下で提供されています。テキサス・インスツルメンツがこれらのリソースを提供することは、適用されるテキサス・インスツルメンツの保証または他の保証の放棄の拡大や変更を意味するものではありません。

お客様がいかなる追加条項または代替条項を提案した場合でも、テキサス・インスツルメンツはそれらに異議を唱え、拒否します。

郵送先住所：Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2025, Texas Instruments Incorporated